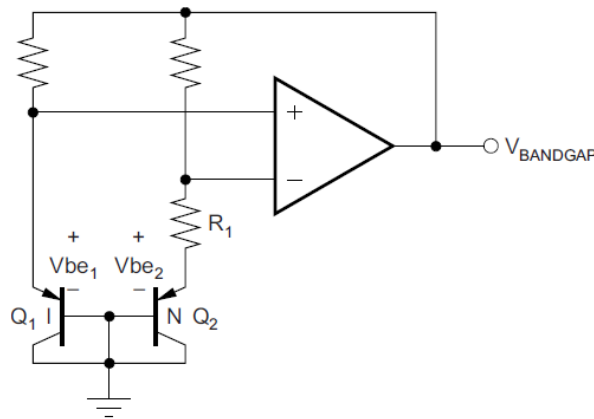


Functional Safety FIT Rate, Failure Mode Distribution REF31xx-Q1

15 ppm/°C Maximum, 100-μA, SOT-23 Series Voltage Reference

Functional Block Diagram



| FIT IEC TR 62380 / ISO 26262-11 (1) | | Per 10 ⁹ Hours (FIT) |
|-------------------------------------|--|---------------------------------|
| Total FIT Rate | | 4 |
| Die FIT Rate | | 2 |
| Package FIT Rate | | 2 |

| FIT Siemens Norm SN29500 (2) | | | |
|------------------------------|--------------------|-------------------------|--------------------------------|
| Table | Category | Ref FIT λ_{ref} | Ref Virtual Tj $\theta_{vj,1}$ |
| Table 4 | Simple Analog / HF | 6 FIT | 45 C |

| Failure Modes | Failure Mode Distribution (%) |
|--|-------------------------------|
| OUT open or HIZ | 40% |
| OUT to GND | 40% |
| OUT operating outside of spec, voltage or timing | 15% |
| Pin to Pin short any two pins | 5% |

(1) Failure Rate, Mission Profile and Failure Modes Distribution

The failure rate and mission profile information come from reliability modeling for Integrated circuits in Reliability data handbook IEC TR 62380 and ISO 26262 Part 11

Mission Profile: Motor Control from Table 11

Power dissipation 1.0 mW

Climate type: World-wide Table 8

Package factor lambda 3 Table 17b

Substrate Material: FR4

EOS FIT rate assumed = 0

(2) Reference failure rate, Virtual (equivalent) junction temperature

The reference failure rate and virtual junction temperature come from Siemens Norm SN29500-2 tables 1-5.

Failure rate for user mission profile is calculated using the reference failure rate and virtual junction temperature and following the calculation information in SN29500-2 section 4.

The failure mode distribution estimation comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment. The failure rates listed reflect random failure events and do not include failures due to misuse or over stress.

REF31xx-Q1 is a catalog product and not compliant to ISO-26262 standards.

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